

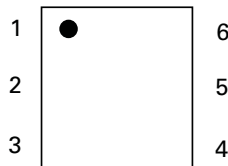
**RoHS Battrax® Series - Single Port Negative - MS-013**



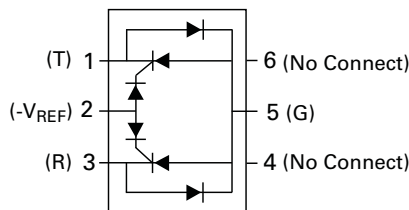
**Agency Approvals**

Agency	Agency File Number
	E133083

**Pinout Designation**



**Schematic Symbol**



**Electrical Characteristics**

Part Number	Marking	$V_{DRM}$ @ $I_{DRM}=5\mu A$	$V_S$ @ 100V/ $\mu s$	$I_H$	$I_S$	$I_T$	$V_T$ @ $I_T=2.2$ Amps	$V_F$	Capacitance*	
		V min	V max	mA min	mA max	A max	V max	V max	pF min	pF max
B1101UCLxx	B1101UC	$-V_{REF} - 1 - 1.2V_I$	$-V_{REF} - 1 + 10V_I$	100	100	2.2	4	5	30	200
B1161UCLxx	B1161UC	$-V_{REF} - 1 - 1.2V_I$	$-V_{REF} - 1 + 10V_I$	160	100	2.2	4	5	30	200
B1201UCLxx	B1201UC	$-V_{REF} - 1 - 1.2V_I$	$-V_{REF} - 1 + 10V_I$	200	100	2.2	4	5	30	200

Notes:  
 - Absolute maximum ratings measured at  $T_A = 25^\circ C$  (unless otherwise noted).  
 - Devices are uni-directional  
 - All electrical characteristics shown are defined from Tip (pin 1) to Ground (pin 5), and Ring (pin 3) to Ground (pin 5)

**Description**

The Battrax® series offers programmable SIDACtor® overvoltage protection devices for SLIC applications. The Single Port Negative Battrax Series provides a programmable device that is referenced to a negative voltage source while internal diodes provide protection from positive surge events.

**Features and Benefits**

- Low voltage overshoot
- Low on-state voltage
- Does not degrade with use
- Fails short circuit when surged in excess of ratings
- Single-port protection
- Gate triggered tracking device
- Integrated diodes for positive voltage

**Applicable Global Standards**

- TIA-968-A
- TIA-968-B
- ITU K.20/21 Enhanced Level
- ITU K.20/21 Basic Level
- GR 1089 Intra-building
- IEC 61000-4-5
- YD/T 1082
- YD/T 993
- YD/T 950

-  $V_{REF}$  Max Value for the negative Battrax is -200 V.  
 - **XX** = Part Number Suffix: **TP** (Tube Pack) or **RP** (Reel Pack).  
 \* Off-state capacitance ( $C_o$ ) is measured across pins 1 & 5 and 3 & 5 at 1 MHz with a 2V bias.

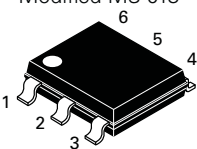
**Surge Ratings**

Series	$I_{PP}$									$I_{TSM}$ 50/60 Hz	di/dt
	0.2x310 <sup>1</sup> 0.5x700 <sup>2</sup>	2x10 <sup>1</sup> 2x10 <sup>2</sup>	8x20 <sup>1</sup> 1.2x50 <sup>2</sup>	10x160 <sup>1</sup> 10x160 <sup>2</sup>	10x560 <sup>1</sup> 10x560 <sup>2</sup>	5x320 <sup>1</sup> 9x720 <sup>2</sup>	10x360 <sup>1</sup> 10x360 <sup>2</sup>	10x1000 <sup>1</sup> 10x1000 <sup>2</sup>	5x310 <sup>1</sup> 10x700 <sup>2</sup>		
	A min	A min	A min	A min	A min	A min	A min	A min	A min		
C	50	500	400	200	150	200	175	100	200	50	500

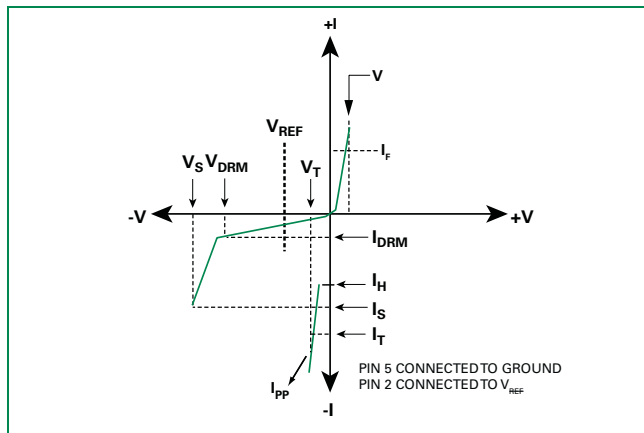
Notes:

- 1 Current waveform in  $\mu s$
- 2 Voltage waveform in  $\mu s$
- Peak pulse current rating ( $I_{PP}$ ) is repetitive and guaranteed for the life of the product.
- $I_{PP}$  ratings applicable over temperature range of -40°C to +85°C ( $I_{PP}$  rating assumes  $V_{REF}$  equals +/- 48 V)
- The device must initially be in thermal equilibrium with -40°C  $\leq T_J \leq$  +150°C

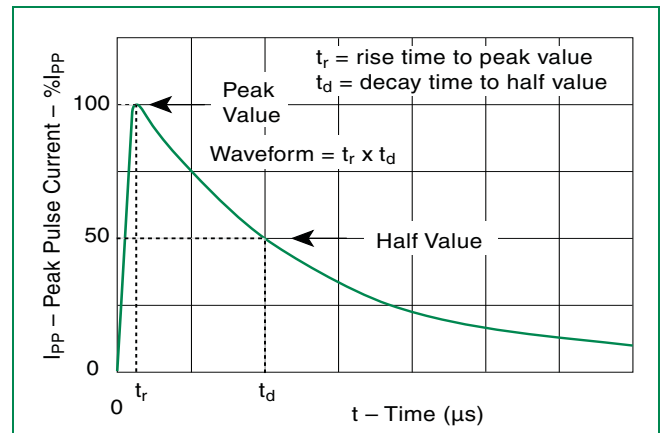
**Thermal Considerations**

Package	Symbol	Parameter	Value	Unit
 Modified MS-013	$T_J$	Operating Junction Temperature Range	-40 to +125	°C
	$T_S$	Storage Temperature Range	-65 to +150	°C
	$R_{\theta JA}$	Thermal Resistance: Junction to Ambient	60	°C/W

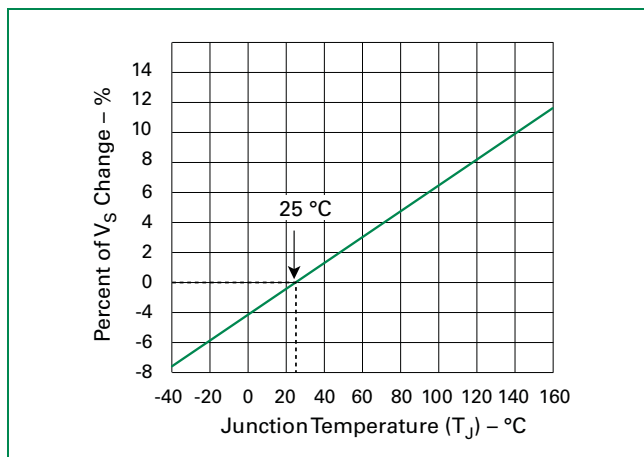
**V-I Characteristics**



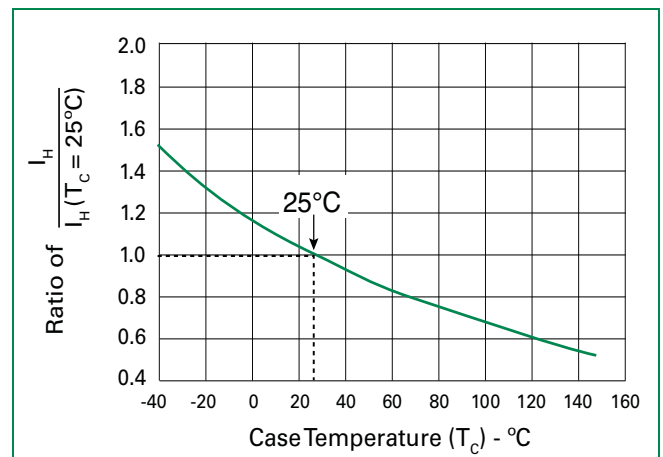
**$t_r \times t_d$  Pulse Waveform**



**Normalized  $V_S$  Change vs. Junction Temperature**

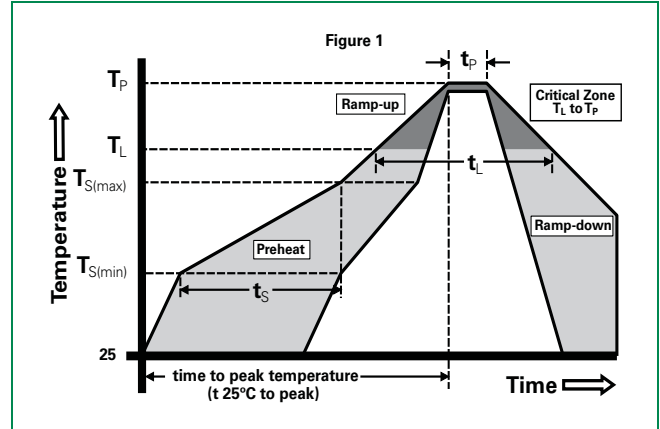


**Normalized DC Holding Current vs. Case Temperature**



**Soldering Parameters**

Reflow Condition		Pb-Free assembly (see Fig. 1)
Pre Heat	-Temperature Min ( $T_{s(min)}$ )	+150°C
	-Temperature Max ( $T_{s(max)}$ )	+200°C
	-Time (Min to Max) ( $t_s$ )	60-180 secs.
Average ramp up rate (LiquidusTemp ( $T_L$ ) to peak)		3°C/sec. Max.
$T_{s(max)}$ to $T_L$ - Ramp-up Rate		3°C/sec. Max.
Reflow	-Temperature ( $T_L$ ) (Liquidus)	+217°C
	-Temperature ( $t_L$ )	60-150 secs.
Peak Temp ( $T_p$ )		+260(+0/-5)°C
Time within 5°C of actual Peak Temp ( $t_p$ )		30 secs. Max.
Ramp-down Rate		6°C/sec. Max.
Time 25°C to Peak Temp ( $T_p$ )		8 min. Max.
Do not exceed		+260°C



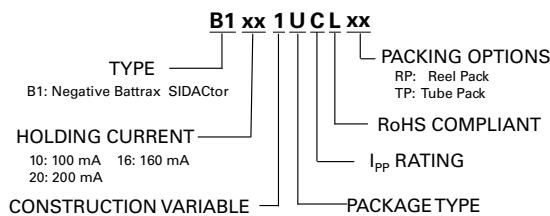
**Physical Specifications**

Lead Material	Copper Alloy
Terminal Finish	100% Matte-Tin Plated
Body Material	UL recognized epoxy meeting flammability classification 94V-0

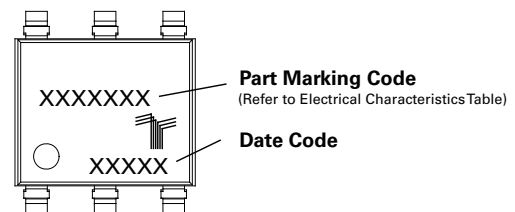
**Environmental Specifications**

High Temp Voltage Blocking	80% Rated $V_{REF}$ Max. ( $V_{DC}$ Peak) +125°C or +150°C, 504 or 1008 hrs. MIL-STD-750 (Method 1040) JEDEC, JESD22-A-101
Temp Cycling	-65°C to +150°C, 15 min. dwell, 10 up to 100 cycles. MIL-STD-750 (Method 1051) EIA/JEDEC, JESD22-A-104
Biased Temp & Humidity	52 $V_{DC}$ (+85°C) 85%RH, 504 up to 1008 hrs. EIA/JEDEC, JESD22-A-101
High Temp Storage	+150°C 1008 hrs. MIL-STD-750 (Method 1031) JEDEC, JESD22-A-101
Low Temp Storage	-65°C, 1008 hrs.
Thermal Shock	0°C to +100°C, 5 min. dwell, 10 sec. transfer, 10 cycles. MIL-STD-750 (Method 1056) JEDEC, JESD22-A-106
Autoclave (Pressure Cooker Test)	+121°C, 100%RH, 2atm, 24 up to 168 hrs. EIA/JEDEC, JESD22-A-102
Resistance to Solder Heat	+260°C, 30 secs. MIL-STD-750 (Method 2031)
Moisture Sensitivity Level	85%RH, +85°C, 168 hrs., 3 reflow cycles (+260°C Peak). JEDEC-J-STD-020, Level 1

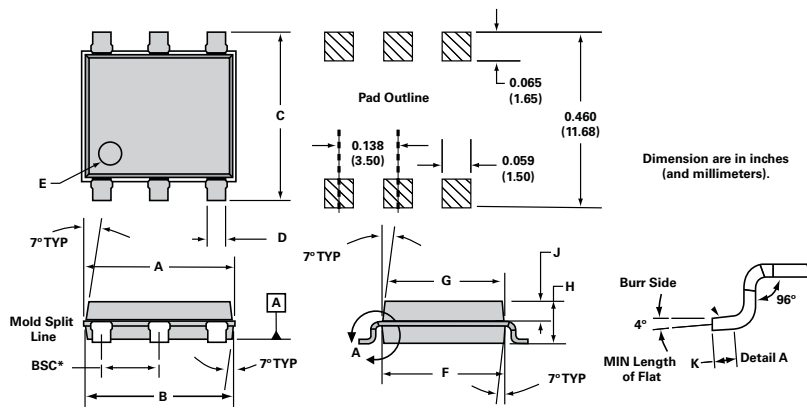
**Part Numbering**



**Part Marking**



**Dimensions — MS-013**



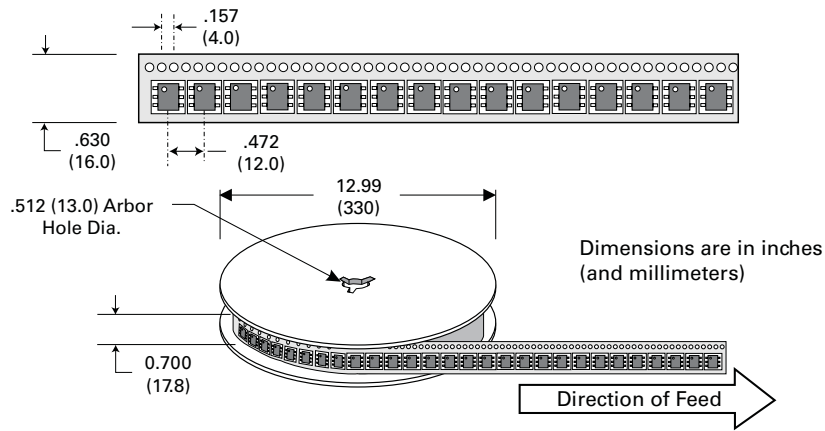
Dimensions	Inches		Millimeters	
	Min	Max	Min	Max
A	0.360	0.364	9.14	9.25
B	0.352	0.356	8.94	9.04
C	0.400	0.412	10.16	10.46
D	0.043	0.045	1.09	1.13
E	0.047	0.055	1.19	1.40
F	0.293	0.297	7.44	7.54
G	0.289	0.293	7.34	7.44
H	0.089	0.093	2.26	2.36
J	0.041	0.049	1.04	1.24
K	0.020		0.51	
<b>BSC*</b>	0.133	0.143	3.38	3.63

\* BSC = Basic Spacing between Centers

**Packing Options**

Package Type	Description	Quantity	Added Suffix	Industry Standard
U	Modified MS-013 6-pin Tape and Reel Pack	1500	RP	EIA-481-D
	Modified MS-013 6-pin Tube Pack	500 (50 per tube)	TP	N/A

**Tape and Reel Specification — MS-013**



**Tube Pack Specification — MS-013**

